

## **SPECIFICATIONS**

Mechanical Contact Retention Force: 1.36KGF min.

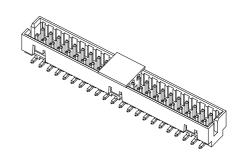
Electrical Current Rating: 2.0A per pin min. Dielectric Withstanding Voltage: 125V AC Dielectric Withstanding Voltage: 1000V

Insulation Resistance: 1000MW min

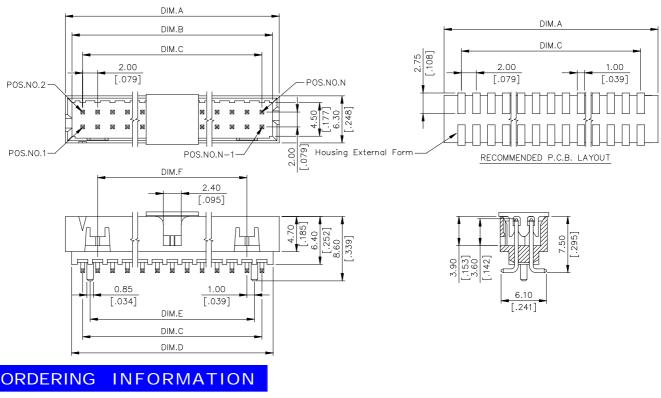
Physical Housing: High Temp. Thermoplastic, Glass Filled, UL94V-0 Contact: Copper Alloy Plating: See "ORDERING INFORMATION" Solder Pad: Copper Alloy Operating Temperature: -55 to +105

## **Header Connector**

HS55 Series Vertical, SMT Type, Plug 2.00mm [.079"] Pitch

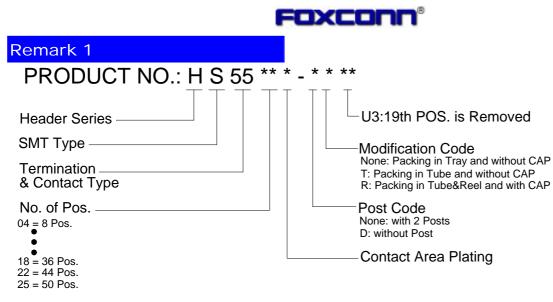


## DRAWING



Please see remark 1

Please see remark 2



F=Gold Flash with Lead Free "RoHS COMPLIANCE" H=30u"Gold with Lead Free "RoHS COMPLIANCE" V=15u"Gold with Lead Free "RoHS COMPLIANCE"

## Remark 2

		52.65	50.85	44.00	51.00	46.00	44.00
HS5525*-***	50						[1.732]
HS5522*-***	44	[2.073]		[1.732]	L .	[1.811]	L J
		46.65	44.85	42.00	45.00	40.00	38.00
		[1.837]	[1.766]	[1.654]	[1.772]	[1.575]	[1.500]
		22.65	20.85	18.00	21.00	16.00	14.00
HS5510*-***	20 18	[.892]	[.821]	[.709]	[.827]	[.630]	[.551]
		20.65	18.85	16.00	19.00	14.00	12.00
HS5509*-***		[.813]	[.742]	[.630]	[.748]	[.551]	[.472]
		18.65	16.85	14.00	17.00	12.00	10.00
HS5508*-***	16	[.734]	[.663]	[.551]	[.669]	[.472]	[.394]
		16.65	14.85	12.00	15.00	10.00	8.00
HS5507*-***	14	[.656]	[.585]	[.472]	[.591]	[.394]	[.315]
		14.65	12.85	10.00	13.00	8.00	
HS5506*-***	12	[.577]	[.506]	[.394]	[.512]	[.315]	
		12.65	10.85	8.00	11.00	6.00	
HS5505*-***	10	[.498]	[.427]	[.315]	[.433]	[.236]	
		10.65	8.85	6.00	9.00	4.00	
HS5504*-***		[.419]	[.348]	[.236]	[.354]	[.157]	
HS5503*-***	6	8.65	6.85	4.00	7.00		
		[.341]	[.270]	[.157]	[.276]		
P/N	POS.	DIM.A	DIM.B	DIM.C	DIM.D	DIM.E	DIM.F